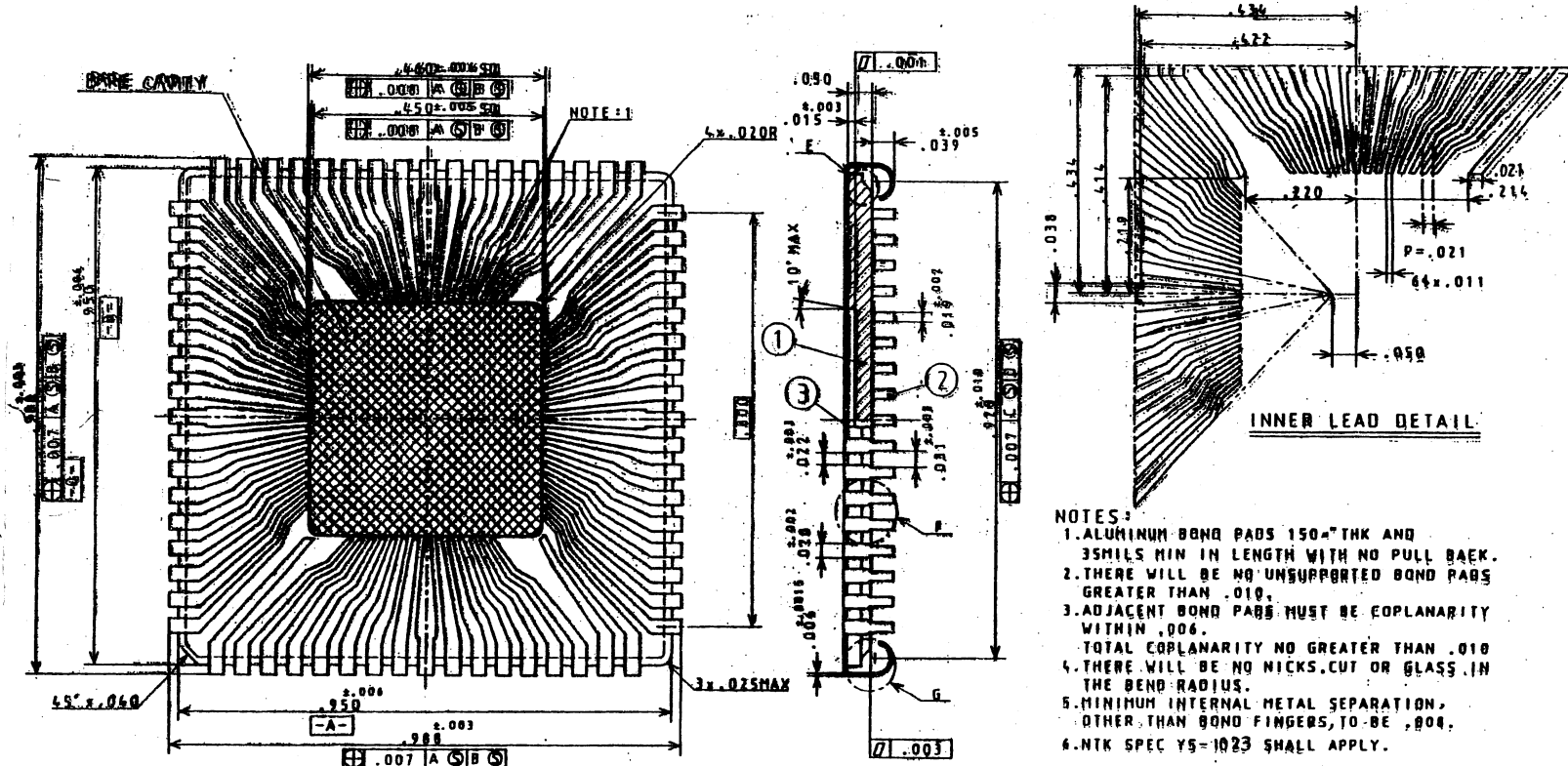
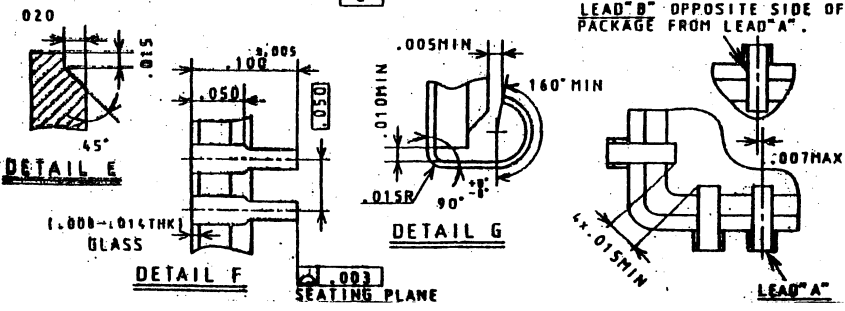


SSM P/N CQJ06827



- NOTES:
1. ALUMINUM BOND PADS 150-THK AND 35MILS MIN IN LENGTH WITH NO PULL BACK.
 2. THERE WILL BE NO UNSUPPORTED BOND PADS GREATER THAN .010.
 3. ADJACENT BOND PADS MUST BE COPLANARITY WITHIN .006. TOTAL COPLANARITY NO GREATER THAN .010
 4. THERE WILL BE NO NICKS, CUT OR GLASS IN THE BEND RADIUS.
 5. MINIMUM INTERNAL METAL SEPARATION, OTHER THAN BOND FINGERS, TO BE .004.
 6. NTK SPEC Y5-1023 SHALL APPLY.



3	SOLDER GLASS	7503BF		
2	LEAD FRAME	ALLOY42		
1	CERAMIC BASE	BLACK ALUMINA		
UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1% N. L. T. 3 DECIMALS, XX ± .01 3 DECIMALS, XXX ± .001		DRAWN <i>M.S.A.S.A.</i> CHECKED <i>g.m.d.</i> APPROVED		
CUSTOMER		WAFERSCALE		
DRW NO.		UNIT	INCH	
		SCALE	1:1	
		DATE	5-21-93	
		TITLE	LEAD "J" CERAMIC QUAD Pkg	
		DATE	1-4-90G01	
		REV. NO.	6820-7003B	
		REV. DESCRIPTION	A-3	

